

## Product Summary

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max T <sub>A</sub> = +25°C
100V	35mΩ @ V <sub>GS</sub> = 10V	6.2A

## Description and Applications

This MOSFET is designed to minimize the on-state resistance (R<sub>DS(ON)</sub>) yet maintain superior switching performance, making it ideal for high-efficiency power-management applications.

- Wireless charging
- DC-DC converters
- Power managements

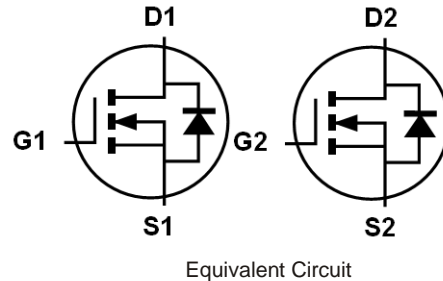
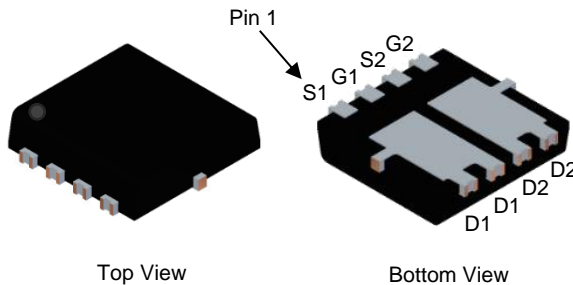
## Features and Benefits

- Rated to +175°C – Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching (UIS) Test in Production – Ensures More Reliable and Robust End Application
- Low R<sub>DS(ON)</sub> – Ensures On-State Losses are Minimized
- Low Input Capacitance
- Fast Switching Speed
- Wetttable Flank for Improved Optical Inspection
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. “Green” Device (Note 3)**
- **This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability.**  
<https://www.diodes.com/quality/product-definitions/>
- **An automotive-compliant part is available under separate datasheet ([DMTH10H032SDVWQ](#))**

## Mechanical Data

- Package: POWERDI@3333-8
- Package Material: Molded Plastic, “Green” Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish — Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208③
- Weight: 0.03 grams (Approximate)

POWERDI@3333-8/SWP (Type UXD)

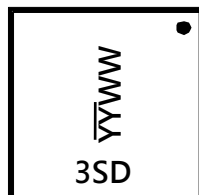


## Ordering Information (Note 4)

Part Number	Package	Packing	
		Qty.	Carrier
DMTH10H032SDVW-7	POWERDI@3333-8/SWP (Type UXD)	2,000	Tape & Reel
DMTH10H032SDVW-13	POWERDI@3333-8/SWP (Type UXD)	3,000	Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free/](http://www.diodes.com/quality/lead_free/) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

## Marking Information



3SD = Product Type Marking Code  
 YYWW = Date Code Marking  
 YY = Last Two Digits of Year (ex: 24 = 2024)  
 WW = Week Code (01 to 53)

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V <sub>DSS</sub>	100	V
Gate-Source Voltage			V <sub>GSS</sub>	±20	V
Continuous Drain Current, V <sub>GS</sub> = 10V (Note 5)	Steady State	T <sub>A</sub> = +25°C	I <sub>D</sub>	6.2	A
		T <sub>A</sub> = +100°C		4.4	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I <sub>DM</sub>	36	A
Maximum Continuous Body Diode Forward Current (Note 5)			I <sub>S</sub>	2.6	A
Pulsed Body Diode Forward Current (10µs Pulse, Duty Cycle = 1%)			I <sub>SM</sub>	36	A
Avalanche Current, L = 0.3mH			I <sub>AS</sub>	13	A
Avalanche Energy, L = 0.3mH			E <sub>AS</sub>	25.3	mJ

**Thermal Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 6)	T <sub>A</sub> = +25°C	P <sub>D</sub>	1.4	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	R <sub>θJA</sub>	107	°C/W
Total Power Dissipation (Note 5)	T <sub>A</sub> = +25°C	P <sub>D</sub>	2.7	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	R <sub>θJA</sub>	55	°C/W
Thermal Resistance, Junction to Case (Note 5)		R <sub>θJC</sub>	5.5	°C/W
Operating and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +175	°C

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS</b> (Note 7)						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	100	—	—	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = 1mA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	—	—	1	µA	V <sub>DS</sub> = 80V, V <sub>GS</sub> = 0V
Gate-Source Leakage	I <sub>GSS</sub>	—	—	±100	nA	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V
<b>ON CHARACTERISTICS</b> (Note 7)						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	2	—	4	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250µA
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	—	27	35	mΩ	V <sub>GS</sub> = 10V, I <sub>D</sub> = 5A
Diode Forward Voltage	V <sub>SD</sub>	—	0.8	1.0	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = 5A
<b>DYNAMIC CHARACTERISTICS</b> (Note 8)						
Input Capacitance	C <sub>ISS</sub>	—	544	—	pF	V <sub>DS</sub> = 50V, V <sub>GS</sub> = 0V, f = 1MHz
Output Capacitance	C <sub>OSS</sub>	—	181	—	pF	
Reverse Transfer Capacitance	C <sub>RSS</sub>	—	6.0	—	pF	V <sub>DS</sub> = 0V, V <sub>GS</sub> = 0V, f = 1MHz
Gate Resistance	R <sub>G</sub>	—	1.2	—	Ω	
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Q <sub>G</sub>	—	4.3	—	nC	V <sub>DS</sub> = 50V, I <sub>D</sub> = 7A
Total Gate Charge (V <sub>GS</sub> = 10V)	Q <sub>G</sub>	—	8.0	—	nC	
Gate-Source Charge	Q <sub>GS</sub>	—	1.8	—	nC	
Gate-Drain Charge	Q <sub>GD</sub>	—	2.4	—	nC	
Turn-On Delay Time	t <sub>D(ON)</sub>	—	8.5	—	ns	V <sub>DS</sub> = 50V, I <sub>D</sub> = 7A V <sub>GS</sub> = 10V, R <sub>GEN</sub> = 6Ω
Turn-On Rise Time	t <sub>R</sub>	—	2.7	—	ns	
Turn-Off Delay Time	t <sub>D(OFF)</sub>	—	11.9	—	ns	
Turn-Off Fall Time	t <sub>F</sub>	—	6.2	—	ns	
Reverse Recovery Time	t <sub>RR</sub>	—	33.2	—	ns	I <sub>F</sub> = 7A, di/dt = 100A/µs
Reverse Recovery Charge	Q <sub>RR</sub>	—	34.3	—	nC	

- Notes:
5. Device mounted on FR-4 substrate PCB, 2oz copper, with thermal bias to bottom layer 1 inch square copper plate.
  6. Device mounted on FR-4 PCB, with minimum recommended pad layout.
  7. Short duration pulse test used to minimize self-heating effect.
  8. Guaranteed by design. Not subject to product testing.

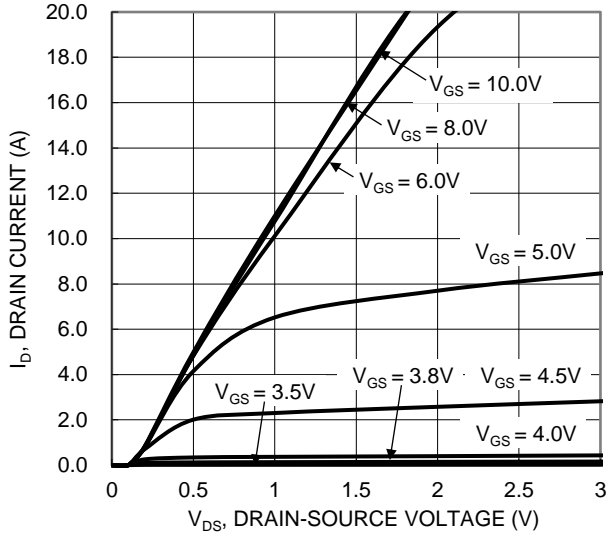


Figure 1. Typical Output Characteristic

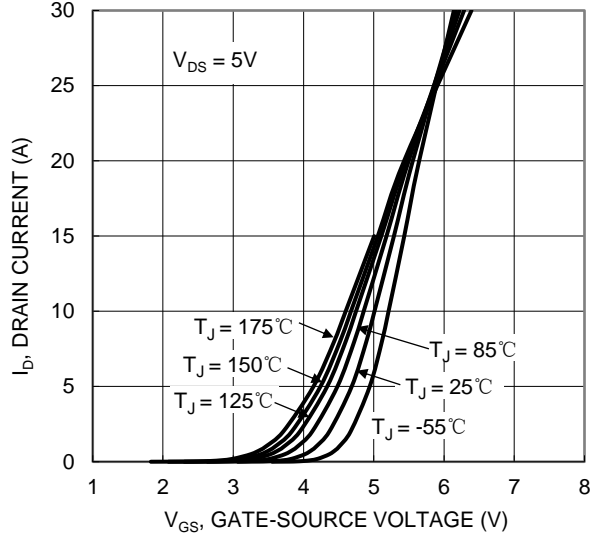


Figure 2. Typical Transfer Characteristic

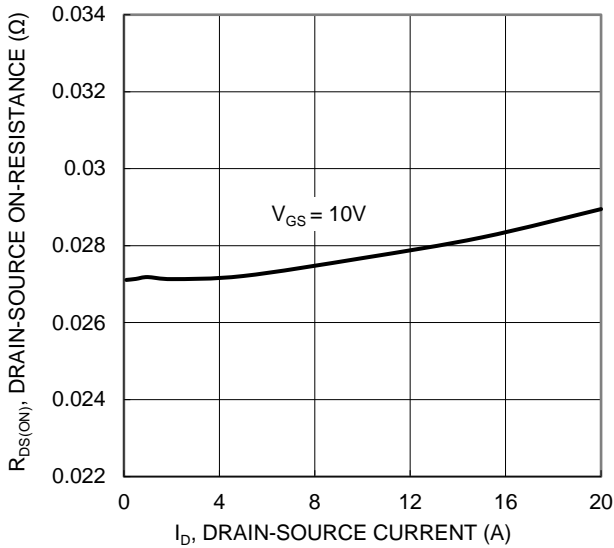


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

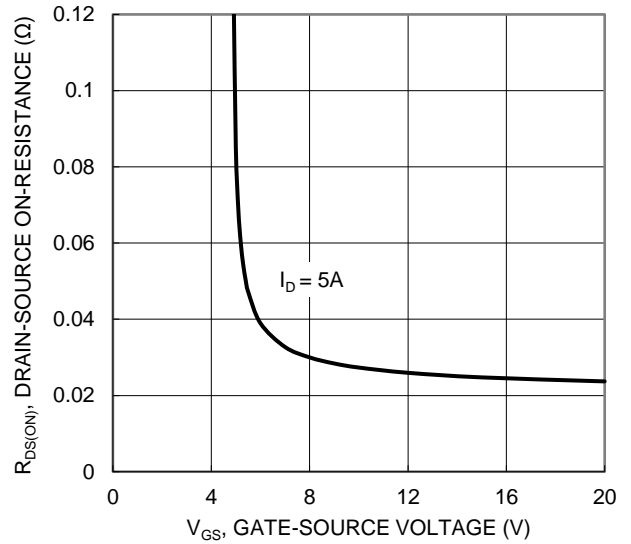


Figure 4. Typical Transfer Characteristic

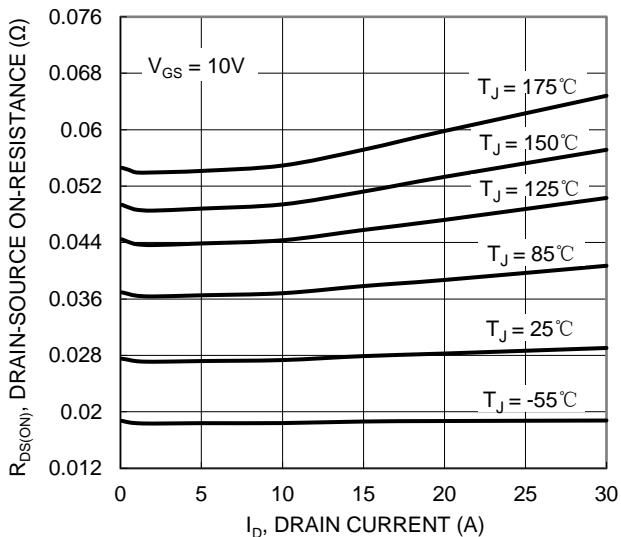


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

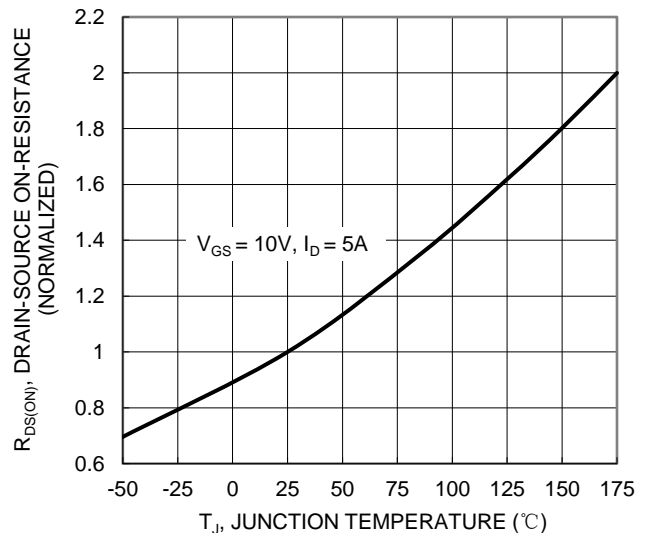


Figure 6. On-Resistance Variation with Temperature

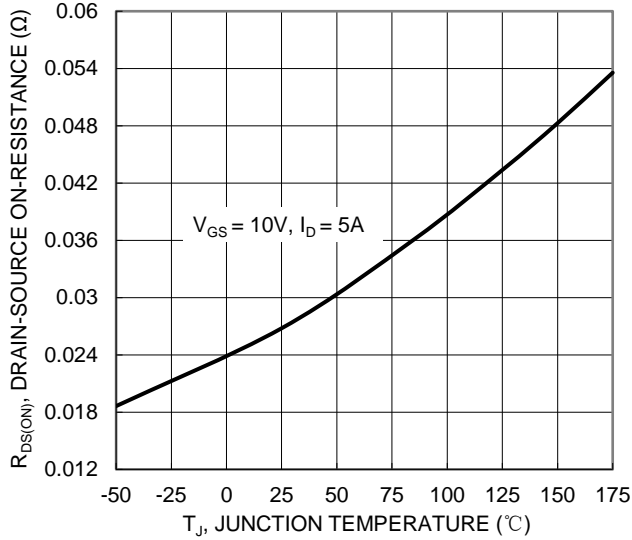


Figure 7. On-Resistance Variation with Temperature

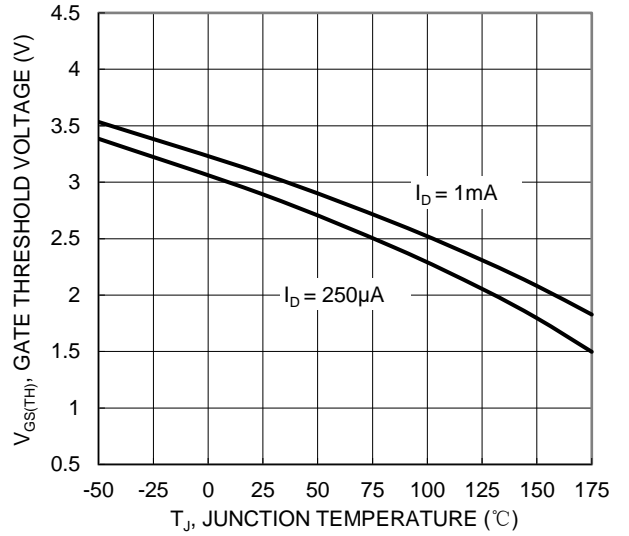


Figure 8. Gate Threshold Variation vs. Junction Temperature

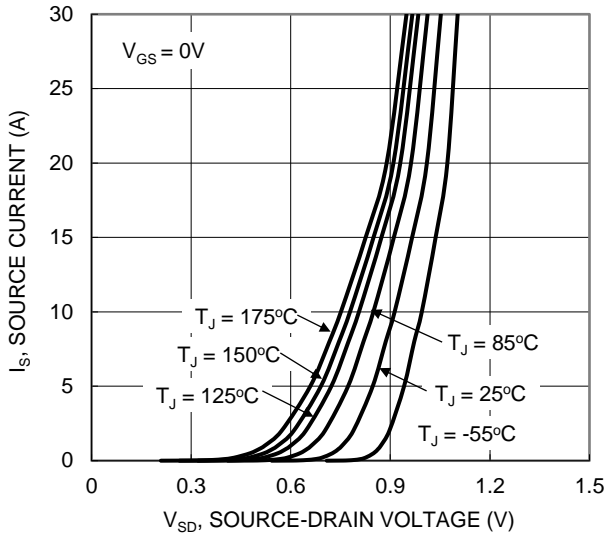


Figure 9. Diode Forward Voltage vs. Current

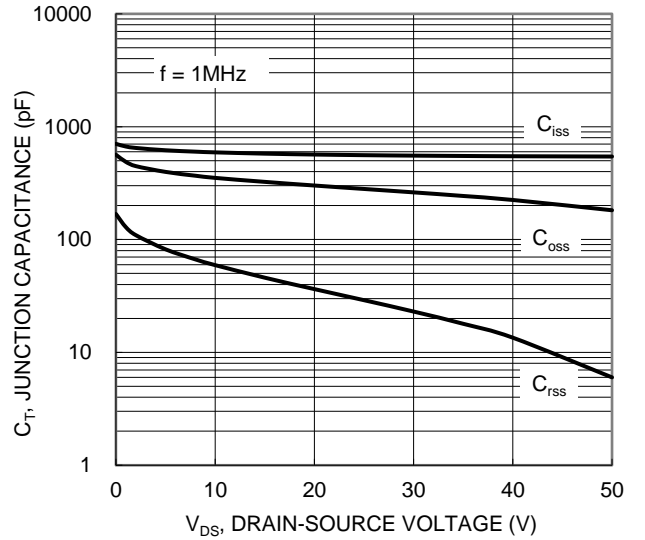


Figure 10. Typical Junction Capacitance

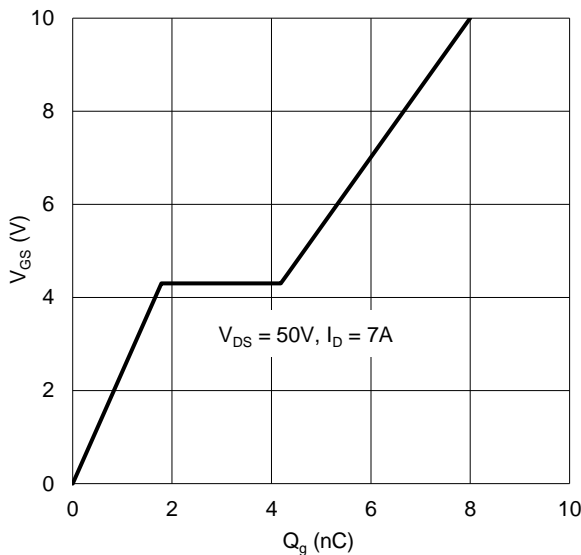


Figure 11. Gate Charge

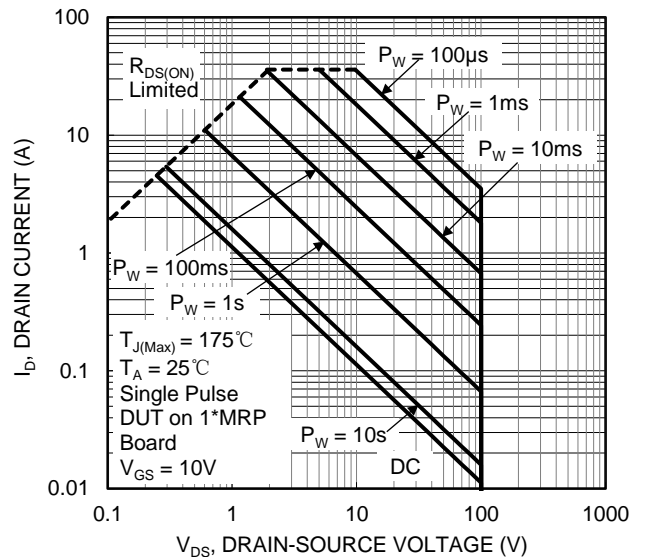


Figure 12. SOA, Safe Operation Area

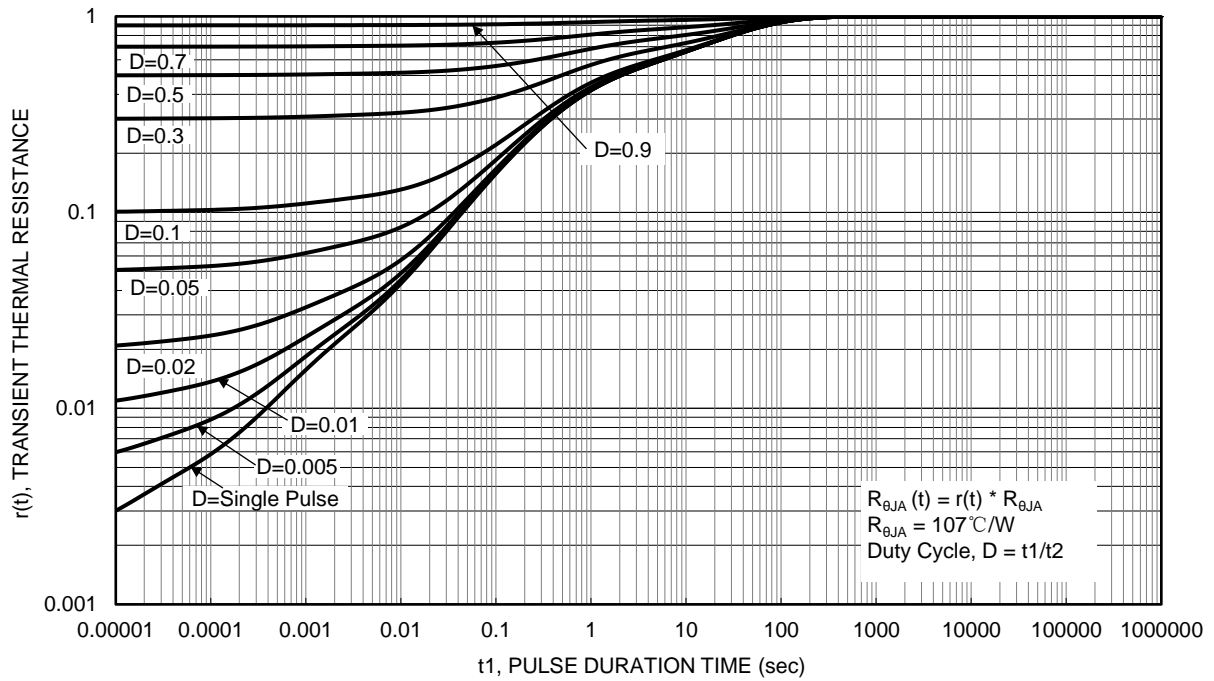
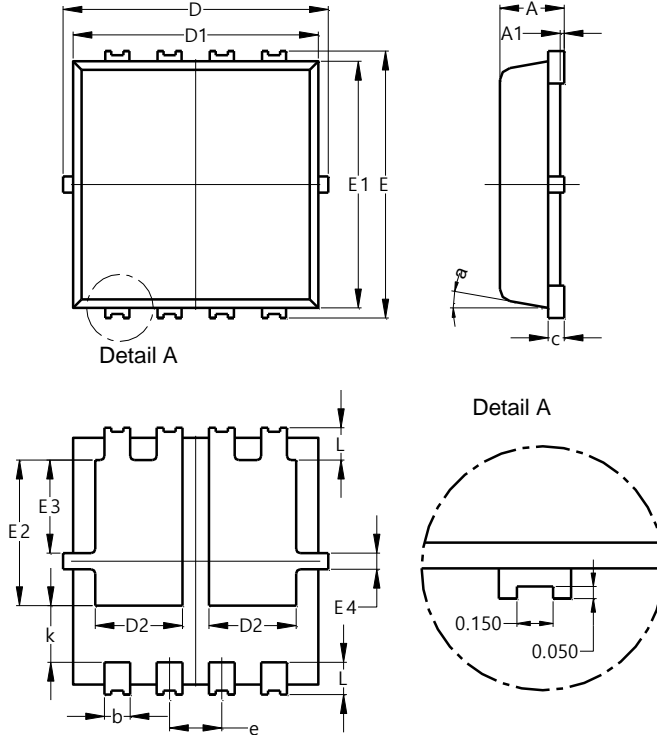


Figure 13. Transient Thermal Resistance

**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**POWERDI®3333-8/SWP (Type UXD)**

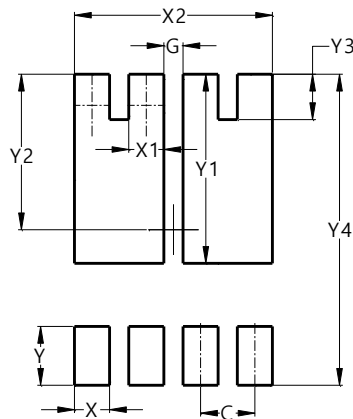


POWERDI®3333-8/SWP (Type UXD)			
Dim	Min	Max	Typ
A	0.75	0.85	0.80
A1	0.00	0.05	–
b	0.25	0.40	0.32
c	0.10	0.25	0.15
D	3.20	3.40	3.30
D1	2.95	3.15	3.05
D2	1.00	1.20	1.10
E	3.20	3.40	3.30
E1	2.95	3.15	3.05
E2	1.60	2.00	1.80
E3	0.95	1.35	1.15
E4	0.10	0.30	0.20
e	–	–	0.65
L	0.30	0.50	0.40
k	0.50	0.90	0.70
a	0°	12°	10°
All Dimensions in mm			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**POWERDI®3333-8/SWP (Type UXD)**



Dimensions	Value (in mm)
C	0.650
G	0.230
X	0.420
X1	0.420
X2	2.370
Y	0.700
Y1	2.250
Y2	1.850
Y3	0.540
Y4	3.700

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